

### **Features**

- · Advanced Trench Process Technology
- · Low Threshold Voltage
- · Fast Switching Speed
- · Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

# N-Channel MOSFET

# **Maximum Ratings**

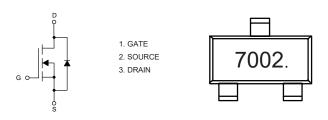
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 115°C/W Junction to Ambient(Note2)

Paramet	Symbol	Rating	Unit		
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Drain Current-Continuous	TA=25°C		0.34	А	
	TA=100°C	- I <sub>D</sub>	0.22		
Pulsed Drain Current	I <sub>DM</sub>	2	А		
Power Dissipation		P <sub>D</sub>	1.08	W	

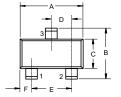
#### Note:

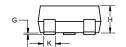
- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of  $R_{\theta JA}$  is measured with the device mounted on  $1 \text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25°C

# **Internal Structure and Marking Code**



# SOT-23

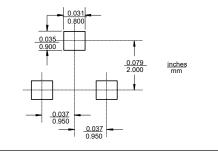






DIMENSIONS						
DIM	INCHES		MM		NOTE	
	MIN	MAX	MIN	MAX	NOTE	
Α	0.110	0.120	2.80	3.04		
В	0.083	0.104	2.10	2.64		
С	0.047	0.055	1.20	1.40		
D	0.034	0.041	0.85	1.05		
Е	0.067	0.083	1.70	2.10		
F	0.018	0.024	0.45	0.60		
G	0.0004	0.006	0.01	0.15		
Н	0.035	0.043	0.90	1.10		
J	0.003	0.007	0.08	0.18		
K	0.012	0.020	0.30	0.51		
L	0.007	0.020	0.20	0.50		

### Suggested Solder Pad Layout



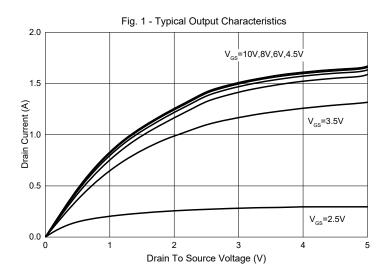


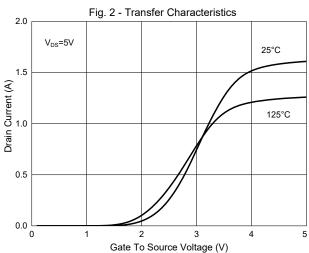
# ELECTRICAL CHARACTERISTICS (Ta=25 $^{\circ}$ C unless otherwise specified)

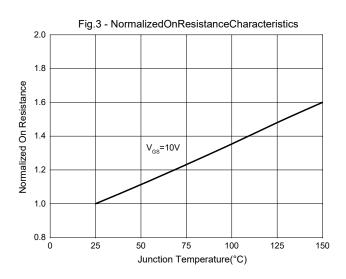
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit	
Static Characteristics	1		I	1	1	1	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.0	1.5	2.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±10	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			80	nA	
Drain-Source On-Resistance	В	V <sub>GS</sub> =10V, I <sub>D</sub> =300mA		1.2	2.5	Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =200mA		1.3 3.0		_ \ \( \O	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA	80			ms	
Diode Forward Voltage	$V_{SD}$	V <sub>GS</sub> =0V, I <sub>S</sub> =300mA			1.2	V	
Diode Forward Current	Is				340	mA	
Static Characteristics				1	1		
Input Capacitance	C <sub>iss</sub>			35		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0V, f=1MHz		5			
Reverse Transfer Capacitance	C <sub>rss</sub>			4			
Reverse Recovrey Charge	Q <sub>rr</sub>			8.5		nC	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =0.34A,di/dt=100A/us		8		ns	
Total Gate Charge	$Q_g$			1.7			
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =30V, $V_{GS}$ =10V , $I_{D}$ =0.34A		0.5		nC	
Gate-Drain Charge	$Q_{gd}$			0.3			
Turn-on Delay Time	t <sub>d(on)</sub>			0.9			
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =30V,V <sub>GS</sub> =10V,		15		- ns	
Turn-off Delay Time	t <sub>d(off)</sub>	$I_D$ =340mA, $R_{GEN}$ =6 $\Omega$		4.5			
Turn-off fall Time	t <sub>f</sub>			33			

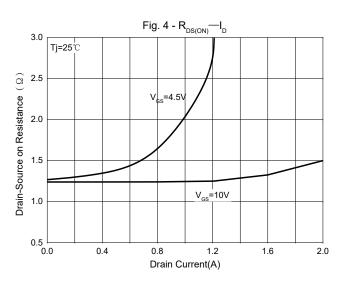


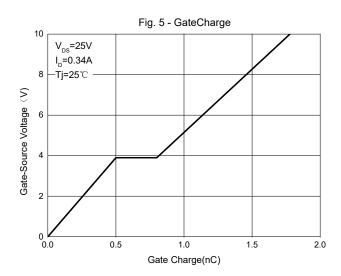
# **Curve Characteristics**

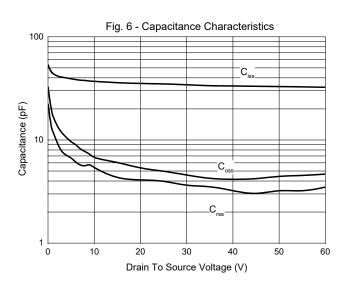






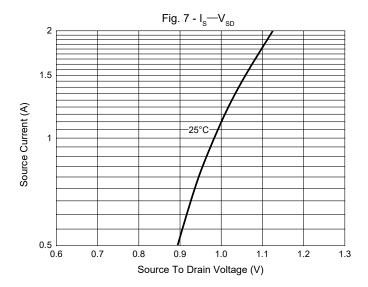


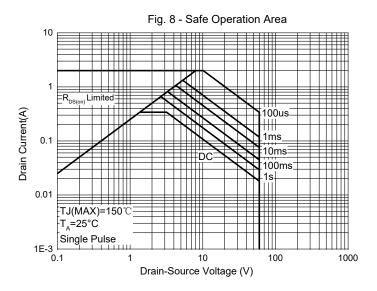


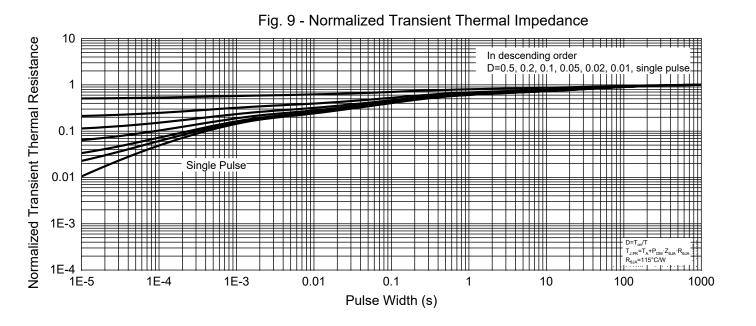




# **Curve Characteristics**







Rev.3-14-10252022 4/5 MCCSEMI.COM



# **Ordering Information**

Device	Packing	
Part Number-TP	Tape&Reel:3Kpcs/Reel	

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